

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Ching-Yu CHANG	09/21/2009
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	No. 8, Li-Hsin Rd. 6
Internal Address:	Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12560164
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ATTORNEY DOCKET NUMBER:	24061.1145
NAME OF SUBMITTER:	David M. O'Dell
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Docket No.: 2008-0519 / 24061.1145
Customer No. 42717

ASSIGNMENT

WHEREAS, I

Ching-Yu Chang of No. 17, Hsinchen Road, Yuansun Village
Yilang County 264, Taiwan, R.O.C.

has invented certain improvements in

METHOD FOR FORMING A SACRIFICIAL SANDWICH STRUCTURE

for which I filed an application for Letters Patent of the United States of America on
September 15, 2009 as U.S. Serial No. 12/560,164; and

WHEREAS, I authorize the attorney of record to update this document to include Patent Office
information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin
Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China is desirous of
obtaining the entire right, title, and interest in, to and under the said invention and the said
application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the
receipt and sufficiency of which is hereby acknowledged, and other good and valuable
consideration, I have sold, assigned, transferred and set over, and by these presents do hereby sell,
assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and
assigns, the entire right, title, and interest in, to and under the said invention, and the said
application, and all divisional, renewal, substitutional, and continuing applications thereof, and all
Letters Patent of the United States of America which may be granted thereon and all reissues and
extensions thereof, and all applications for Letters Patent which may be filed for said invention in
any country or countries foreign to the United States of America, and all extensions, renewals,
and reissues thereof, and all prior patents and patent applications from which a filing priority of
the above-described patent application may be obtained, including the right to collect past
damages; and I hereby authorize and request the Commissioner of Patents of the United States of
America, and any official of any country or countries foreign to the United States of America,
whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said
invention to the said TSMC, its successors, legal representatives and assigns, in accordance with
the terms of this instrument.

AND I HEREBY covenant that I have full right to convey the entire interest herein assigned, and
that I have not executed, and will not execute, any agreement in conflict herewith.

AND I HEREBY further covenant and agree that I will communicate to said TSMC, its
successors, legal representatives and assigns, any facts known to us respecting said invention, and
testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal,
substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths
and generally do everything possible to aid the said TSMC, its successors, legal representatives
and assigns, to obtain and enforce proper patent protection for said invention in all countries.

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Inventor Name: Ching-Yu Chang

Residence Address: No. 17, Hsinchen Road, Yuansun Village
Yilang County 264, Taiwan, R.O.C.

Dated: Sep. 2 / 09

Ching - Yu Chang
Inventor Signature